Claims

1. An encapsulation for an organic electronic component, characterized in that the component, encapsulated in a dimensionally stable capsule, is at least partially covered with a protective film.

2. The encapsulation as in claim 1, wherein said dimensionally stable capsule is glued to the substrate.

3. The encapsulation as in either of claims 1 or 2, wherein the entire exterior of the component is covered with a protective film.

4. The encapsulation as in one of the preceding claims, wherein said protective film includes at least one thin-barrier film.

5. The encapsulation as in one of the preceding claims, wherein said protective film includes a film made of silicon nitride.

6. The encapsulation as in one of the preceding claims, wherein said protective film includes a layer made of parylene C.

7. The encapsulation as in one of the preceding claims, wherein said protective film has a thickness in the range of 1 nm to 500 μm.

8. A method for producing an encapsulation, wherein an organic electronic component on a substrate is first covered with a capsule, the capsule is then fixed to the substrate, and the encapsulated component is thereafter covered at least in part with a protective film.

9. The method as in claim 8, wherein said capsule is glued to said substrate.

10. The method as in either of claims 8 or 9, wherein said protective film is applied to said encapsulated component by a method selected from the group including the following methods:
chemical vapor deposition, physical vapor deposition, wet chemical deposition, such as spin coating, dip coating, drop coating, printing techniques such as stencil printing, squeegee printing, screen printing, ink jet processes, spraying, plasma coating methods, plasma polymerization methods, laminating processes, hot sealing, transfer techniques (such as thermotransfer), welding methods and injection molding.

11. The method as in one of claims 8 to 10, wherein the application of the protective film takes place at least in part under reduced pressure.

12. The method as in one of claims 8 to 10, wherein the application of the protective film takes place at least in part in a high vacuum.

12. The method as in one of claims 8 to 11, wherein the protective film takes place at least in part via chemical vapor deposition.[5]

13. The method as in claim 12, wherein said chemical vapor deposition is plasma-assisted.

14. The method as in one of claims 8 to 13, wherein the contacting of the component by means of, inter alia, a connection cable bringing said organic electronic component into contact with an external drive or playback electronics and/or another type of connection (grounding) takes place prior to the application of said thin-barrier film protective film.

15. The use of an encapsulation according to one of the preceding claims to protect organic electronic components, such as organic light-emitting diodes, polymer chips and/or organic photovoltaic and/or electrochromic elements and/or display applications that are organically based.

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[5]Translator's Note: Phraseology sic; repetition of claim number sic.